MSG43001

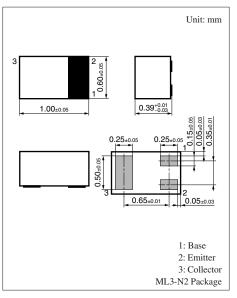
SiGe HBT type

For low-noise RF amplifier

Features

- · Compatible between high breakdown voltage and high cutoff frequency
- Low-noise, high-gain amplification
- Suitable for high-density mounting and downsizing of the equipment for Ultraminiature leadless package $0.6 \text{ mm} \times 1.0 \text{ mm}$ (height 0.39 mm)

Absolute Maximum Ratings $T_a = 25^{\circ}C$							
Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V _{CBO}	9	V				
Collector-emitter voltage (Base open)	V _{CEO}	6	V				
Emitter-base voltage (Collector open)	V _{EBO}	1	V				
Collector current	I _C	30	mA				
Collector power dissipation*	P _C	100	mW				
Junction temperature	Tj	125	°C				
Storage temperature	T _{stg}	-55 to +125	°C				



Marking Symbol: 3N

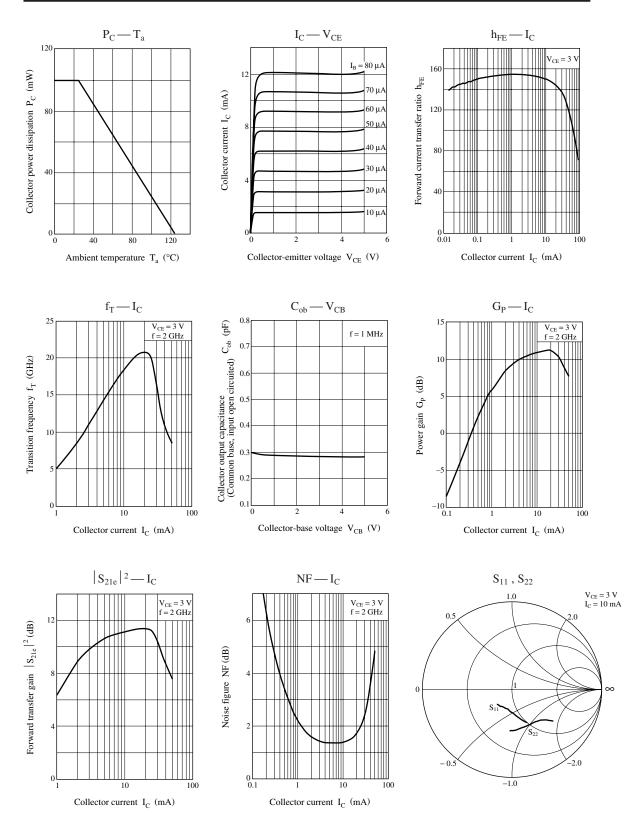
Note) *: Copper plate at the collector is 5.0 cm^2 on substrate at $10 \text{ mm} \times 12$ $mm \times 0.8 mm$.

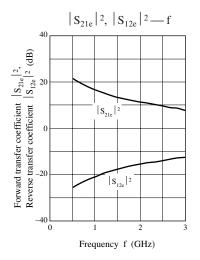
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 9 V, I_E = 0$			1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 6 V, I_B = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 1 V, I_C = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 3 V, I_C = 3 mA$	100		220	
Transition frequency	f _T	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}, f = 2 \text{ GHz}$		19		GHz
Forward transfer gain	S _{21e} ²	$V_{CE} = 3 \text{ V}, I_{C} = 10 \text{ mA}, f = 2 \text{ GHz}$	9.0	11.0		dB
Noise figure	NF	$V_{CE} = 3 V, I_C = 3 mA, f = 2 GHz$		1.4	2.0	dB
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 3 V, I_E = 0, f = 1 MHz$		0.3	0.6	pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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